Application No. 09/681,304

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6-11-02

T. Flocoors

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: R.J. Saia et al.
Application No. 09/681,304
Filed: 15 March 2001

: Group Art Unit: 2814
: Examiner: D. Nguyen
: Response to Paper No. 5

For   **Microelectromechanical System Device Package and Packaging Method**

AMENDMENT UNDER 37 CFR 1.111

Assistant Commissioner for Patents
Washington, DC 20231

In response to the Office Action dated 26 March, please amend the above-identified application as follows.

IN THE CLAIMS:

Please cancel claims 5, 9-15, 17-18, and 20-25.
Please rewrite claims 1, 7, and 16 as follows:

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1 (amended).   A method for packaging a microelectromechanical system (MEMS) device comprising:

using a partially-cured adhesive to attach a release sheet to a MEMS package flexible layer;

providing a cavity having a smooth surface perimeter and extending through the release sheet and at least partially through the MEMS package flexible layer;

removing the release sheet; and

attaching the MEMS device to the MEMS package flexible layer with a MEMS structure of the MEMS device being positioned within the cavity.

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7 (amended).   A method for packaging a microelectromechanical system (MEMS) device comprising:

using a partially-cured adhesive to attach a release sheet to a MEMS package flexible layer;

providing a cavity extending through the release sheet and partially through the MEMS package flexible layer;

providing a protective coating in the cavity;

then removing the release sheet; and

attaching the MEMS device to the MEMS package flexible layer with a MEMS structure of the MEMS device being positioned within the cavity.